



PATENT  
(5201-25300/01-120)

UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:  
Hsiung et al.

Serial No. 09/885,687

Filed: June 19, 2001

For: SEMICONDUCTOR DEVICE  
PACKAGE SUBSTRATE PROBE  
FIXTURE

Group Art Unit: 2829  
Examiner: Nguyen, T.

Atty. Dkt. No. 5201-24300

#5/Drawings  
Changes  
1.48  
1/22/03

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: **Box Non-Fee Amendment**, Assistant Commissioner of Patents, Washington, D.C. 20231, on the date indicated below:

January 9, 2003  
Date

Kevin L. Daffer

**REQUEST FOR APPROVAL OF DRAWING CHANGES UNDER 37 C.F.R. §1.121**

**Box Non-Fee Amendment**  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Pursuant to 37 C.F.R. §1.121(a)(3), it is respectfully requested that the changes shown in red on the attached drawings be approved by the Examiner in the above-referenced case. As shown on the attached Drawings, please include the crosshatchings for metallic solder bumps 110, solder balls 150, and bonding pads 105 and 155. Non-metallic material need not be cross-hatched pursuant to MPEP 608.02. These changes are further discussed within the accompanying Response to Office Action in the Remarks section under the heading of Objections to Drawings. These changes do not present new matter.

Respectfully submitted,

Kevin L. Daffer  
Reg. No. 34,146  
Attorney for Applicant(s)

Conley, Rose & Tayon, P.C.  
P.O. Box 398  
Austin, TX 78767-0398  
Ph: (512) 476-1400  
Date: January 9, 2003  
HNTT

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